LNJ316C8TRA

Surface Mounting Chip LED

Microlens Type

Absolute Maximum Ratings $T_a = 25^{\circ}C$

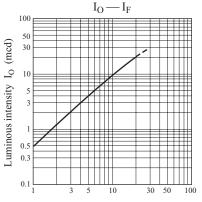
Parameter	Symbol	Rating	Unit	
Power dissipation	P _D	60	mW	
Forward current	I _F	20	mA	
Pulse forward current *	I _{FP}	100	mA	
Reverse voltage	V _R	4	V	
Operating ambient temperature	T _{opr}	-30 to +85	°C	
Storage temperature	T _{stg}	-40 to +100	°C	

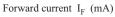
Lighting Color

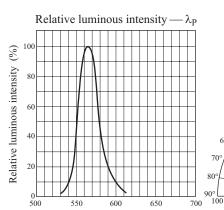
Note) *: The condition of IFP is duty 10%, Pulse width 1 msec.

Electro-Optical Characteristics $T_a = 25^{\circ}C$

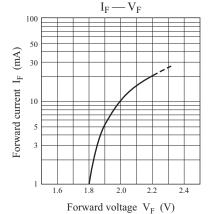
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity	I _O	$I_F = 10 \text{ mA}$	3.3	8.8		mcd
Reverse current	I _R	$V_R = 4 V$			10	μΑ
Forward voltage	V _F	$I_{\rm F} = 10 {\rm mA}$		2.03	2.6	V
Peak emission wavelength	$\lambda_{\rm P}$	$I_{\rm F} = 10 {\rm mA}$		565		nm
Spectral half band width	Δλ	$I_{\rm F} = 10 \text{ mA}$		30		nm







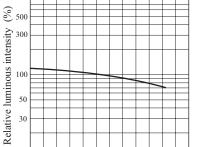
Peak emission wavelength $\lambda_P~(nm)$



Directive characteristics

60

80



Relative luminous intensity

1 0 0 0

00

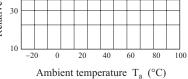
80 60

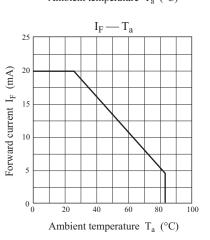
40

20

0

- Ta





Relative luminous intensity (%)

20 40 60 80

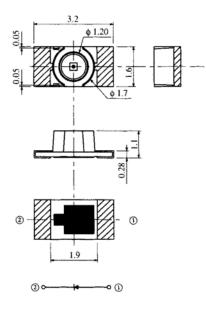
[•] Yellow Green

LNJ316C8TRA

Panasonic

Package (Unit: mm)

KLTLTN2K1600



• Pin name

1: Anode

2: Cathode

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